

### Features

- Easy-to-use standalone high-efficiency 1-cell switching charger
  - Proprietary sensorless charge current control
  - 4.1V to 6.2V input voltage with 28V absolute maximum input voltage rating
  - Charge voltages: 4.20V / 4.35V / 4.40V
  - 2A maximum fast charge current
  - 1.2MHz switching frequency
  - 93% high efficiency @ VBAT=3.8V, ICHG=1A
  - 89% high efficiency @ VBAT=3.8V, ICHG=2A
  - Input voltage regulation to allow weak input power source to charge battery (VINDPM)
  - Support trickle charge, precharge, Constant Current (CC) charge, Constant Voltage (CV) charge, charge termination and recharge
- High charge accuracy
  - +/- 0.5% charge voltage regulation
  - +/- 10% charge current regulation
- High integration
  - Integrated all MOSFETs
  - Internal loop compensation
  - LED charge indication driver
- Protections
  - Cycle-by-cycle current limit protection
  - Input over-voltage protection (OVP)
  - Cold/hot battery temperature monitoring
  - Junction temperature thermal regulation
  - ISET pin short and open protection
- Packaging
  - DFN3x3-10
  - RoHS compliant and halogen free
  - 100% lead (Pb) free

### Applications

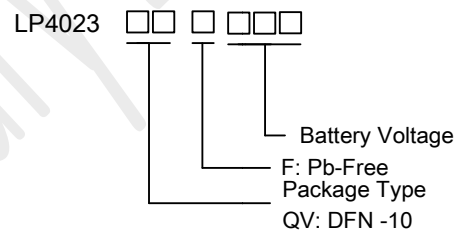
- Portable battery powered devices
- Gaming devices
- Charging docks and cradles
- E-Cigarette

### General Description

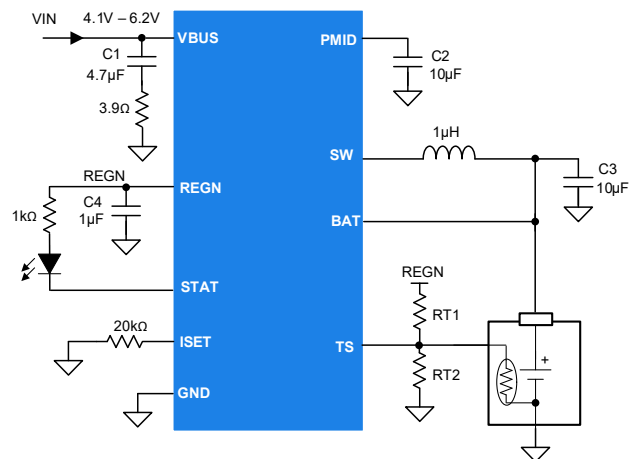
The LP4023 is a standalone 1-cell switching battery charger providing up to 2A charge current to the battery from 4.1V to 6.2V input voltage. The charge current is programmable by a resistor connected from ISET to GND. The charge can be enabled and disabled from ISET pin. The LP4023 operates at 1.2MHz switching frequency allowing a small-size 1uH inductor for 2A fast charging. The LPS patent-protected integrated current sensing and control technique eliminates external sensing resistor and allows high charge efficiency, low BOM cost and very small footprint.

The LP4023 is available in DFN3x3-10 packages. LP4023 is pin-to-pin compatible with LP4032.

### Order Information



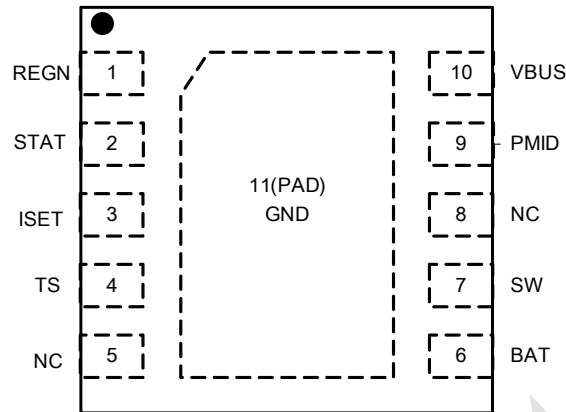
### Application Circuit



## Device Information

Part Number	Battery Voltages	Top Marking	Package	Moisture Sensitivity Level	Shipping
LP4023QVF	4.2V	LPS LP4023 YWX	DFN3x3-10	MSL3	5K/REEL
LP4023QVF-435	4.35V	LPS LP4023 435YWX	DFN3x3-10	MSL3	5K/REEL
LP4023QVF-440	4.40V	LPS LP4023 440YWX	DFN3x3-10	MSL3	5K/REEL
Marking indication: Y: Year code. W: Week code. X: Batch numbers.					

## Pin Diagram



DFN3x3-10 (Top View)

## Pin Description

Pin Name	Pin#	Description
REGN	1	Bias output, internally connected to PMID. Place a 1uF ceramic capacitor from REGN to GND.
STAT	2	Charge status indication output. Connect a LED from REGN pin to STAT pin via a current limiting resistor. The STAT pin indicates charger status: <ul style="list-style-type: none"> <li>• Charge in progress: STAT pin is pulled LOW</li> <li>• Charge complete: STAT pin is OPEN</li> </ul>
ISET	3	Charge current program input. Connect a 1% resistor RISET from this pin to ground to program the charge current. If ISET pin is floating or pulled up higher than 1V, charge current is minimized. If ISET pin is pulled below 0.35V, charge is disabled.
TS	4	Battery temperature sense thermistor input. Charge is suspended if the battery thermistor temperature is out of range. Leave the TS pin floating if TS pin function is not used.
NC	5,8	Not connected internally
BAT	6	Battery connection pin. Connect this pin to node of inductor output terminal and battery pack positive terminal. A 10uF capacitor is recommended to connect to this node.
SW	7	Switching node.
PMID	9	Output of the source of over voltage protection N-channel MOSFET (OVPFET) . Place ceramic 10μF between PMID to GND and place it as close as possible to IC. PMID voltage is clamped once VBUS over voltage is detected.
VBUS	10	Charger input connection. Place a 2.2uF or higher ceramic capacitor from VBUS to GND. To dampen potential voltage spike due to parasitic inductance and input capacitor oscillation, a resistor is connected in series with input capacitor.
GND	11	Power ground and analog ground.

## Absolute Maximum Ratings <sup>(1)</sup>

VBUS voltage to GND-----	-0.3V to 28V
REGN, PMID, SW Voltage to GND-----	-0.3V to 7V
BAT Voltage to GND -----	-0.3V to 6V <sup>(2)</sup>
STAT, ISET, TS Voltages to GND -----	-0.3V to 6V
STAT Sink Current-----	6mA
REGN Source Current -----	16mA
Maximum Junction Temperature (T <sub>j</sub> )-----	150°C
Storage Temperature Range-----	-40°C to 150°C
Maximum Soldering Temperature (at leads, 10 sec)-----	260°C

**Note1:** Stresses beyond those listed under “Absolute Maximum Ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

**Note 2:** Surge protection is internally built in at BAT pin to stand voltage surge at this pin.

## ESD Ratings

HBM (Human Body Model) -----	4kV
MM (Machine Model)-----	200V
CDM (Charge Discharge Model) -----	2kV

## Thermal Information

θ <sub>JA</sub> (Junction-to-Ambient Thermal Resistance) -----	45°C/W
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## Recommended Operating Conditions

SYMBOL	PARAMETER	MIN	TYP	MAX	UNIT
V <sub>IN</sub>	Input Voltage	4.1		6.2	V
I <sub>CHG</sub>	Fast Charge Current	0.35		2.3	A
V <sub>BAT</sub>	Battery Charge Voltage		4.2 / 4.35		V
T <sub>J</sub>	Operating Junction Temperature Range (T <sub>J</sub> )	-40		125	°C
T <sub>A</sub>	Ambient Temperature Range	-40		85	°C
L	Output Inductance	0.7	1	2.64	μH
C <sub>IN</sub>	Input Capacitance at VBUS	0.66	2.2 or 4.7		μF
C <sub>PMID</sub>	PMID Capacitance	3	10		μF
C <sub>BAT</sub>	BAT Capacitance	3	10		μF

### Notes:

(1) The values recommended in the table are effective inductance and capacitance.

## Electrical Characteristics

(The (The specifications are at  $V_{VBUS\_LOWV} < V_{VBUS} < V_{VBUS\_OVP}$  and  $V_{VBUS} > V_{BAT} + V_{SLEEP}$ ,  $L=1\mu H$ ,  $T_J = 25^\circ C$  unless otherwise noted)

SYMBOL	PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
QUIESCENT CURRENT						
$I_{Q\_BAT}$	Battery reverse current	$V_{BAT} = V_{SW} = 4.35V$ , VBUS pin is floating			1	$\mu A$
$I_{Q\_BAT}$	Battery leak current	Charge is terminated, $V_{BAT}=4.35V$			5	$\mu A$
$I_{Q\_BAT}$	Battery leak current	ISET pin short to GND, $V_{BAT}=4.35V$			5	$\mu A$
OVER VOLTAGE PROTECTION						
$V_{VBUS\_OVP\_RISE}$	VBUS input overvoltage threshold	$V_{VBUS}$ rising	6.2	6.4	6.6	V
$V_{VBUS\_OVP\_HYS}$	VBUS input overvoltage threshold hysteresis	$V_{VBUS}$ falling		0.5		V
$V_{PMID\_CLAMP}$	PMID voltage	PMID voltage at $V_{VBUS}=12V$		5		V
MOSFETS						
$R_{DS(on)\_Q1}$	OVPFET on-resistance	$V_{VBUS}=5V$		70		m $\Omega$
$R_{DS(on)\_Q2}$	HSFET on-resistance	$V_{VBUS}=5V$		75		m $\Omega$
$R_{DS(on)\_Q3}$	LSFET on-resistance	$V_{VBUS}=5V$		170		m $\Omega$
INPUT VOLTAGE						
$V_{VBUS}$	VBUS operation range		4.1		6.2	V
$V_{UVLO\_RISE}$	Under voltage lock out(UVLO) voltage	$V_{VBUS}$ rising	3.65	3.75	3.85	V
$V_{UVLO\_FALL}$	UVLO voltage	$V_{VBUS}$ falling		300		mV
$V_{SLEEP}$	Into sleep mode threshold	$V_{VBUS}$ falling, $V_{BAT} - V_{VBUS}$	30	60	90	mV
$V_{SLEEPZ}$	Exit sleep mode threshold	$V_{VBUS}$ rising, $V_{VBUS}-V_{BAT}$	140	180	230	mV
$V_{INDPM\_MIN}$	Minimum VINDPM at VBUS	$V_{BAT}=3.5V$ Regulated at VBUS pin	3.9	4.0	4.1	V
ISET Pin						
$V_{ISET}$	ISET pin voltage		0.985	1	1.015	V
$K_{ICHG}$	Charge current ratio	$R_{ISET} = 23.2k\Omega, 40.2k\Omega$ $ICHG=K_{ICHG}/R_{ISET}$	10%	40	10%	Axk $\Omega$
$K_{ICHG}$	Charge current ratio	$R_{ISET} = 78.7k\Omega$ $ICHG=K_{ICHG}/R_{ISET}$	15%	40	15%	Axk $\Omega$
$V_{ISET\_LOW}$	ISET voltage low			0.35		V

## Electrical Characteristics

(The specifications are at  $V_{VBUS\_LOWV} < V_{VBUS} < V_{VBUS\_OVP}$  and  $V_{VBUS} > V_{BAT} + V_{SLEEP}$ ,  $L=1\mu H$ ,  $T_J = 25^\circ C$  unless otherwise noted)

SYMBOL	PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
<b>BATTERY CHARGER</b>						
$V_{BATREG}$	Charge voltage	CV regulation voltage at BAT pin	4.179	4.2	4.221	V
			4.328	4.35	4.372	V
			4.367	4.40	4.433	V
$I_{CHG}$	Fast charge current	$I_{CHG}=2A, V_{VBUS}=5V, V_{BAT}=3.8V$ $R_{ISET}=20k\Omega$	1800	2000	2200	mA
$I_{CHG}$	Fast charge current	$I_{CHG}=1A, V_{VBUS}=5V, V_{BAT}=3.8V$ $R_{ISET}=40k\Omega$	900	1000	1100	mA
$I_{PRECHG}$	Precharge current	$I_{CHG}=2A, V_{VBUS}=5V, V_{BAT}=2.5V$ $R_{ISET}=20k\Omega$	140	200	260	mA
$I_{PRECHG}$	Precharge current	$I_{CHG}=1A, V_{VBUS}=5V, V_{BAT}=2.5V$ $R_{ISET}=40k\Omega$	60	100	140	mA
$I_{BAT\_SHORT}$	Trickle charge current	$V_{VBUS}=5V, V_{BAT}=1.0V$	45	60	75	mA
$I_{TERM}$	Termination current	$I_{CHG}=1A, V_{BATREG}=4.2V$ $R_{ISET}=20k\Omega$	140	200	260	mA
$I_{TERM}$	Termination current	$I_{CHG}=1A, V_{BATREG}=4.2V$ $R_{ISET}=40k\Omega$	60	100	140	mA
$V_{BAT\_SHORT\_RISE}$	$V_{BAT}$ short rising threshold	From battery short to precharge	1.85	2.00	2.15	V
$V_{BAT\_SHORT\_FALL}$	$V_{BAT}$ short falling threshold	From precharge to battery short	1.65	1.80	1.95	V
$V_{BAT\_LOWV\_RISE}$	$V_{BAT}$ fast charge rising threshold	Precharge to fast charge	2.9	3.0	3.1	V
$V_{BAT\_LOWV\_FALL}$	$V_{BAT}$ fast charge falling threshold	Fast charge to precharge	2.6	2.7	2.8	V
$V_{RECHG\_HYS}$	Recharge threshold	$V_{BAT}$ falling	120	150	180	mV
<b>STAT</b>						
$I_{STAT\_PD}$	STAT pull-down current				6	mA

## Electrical Characteristics

(The specifications are at  $V_{VBUS\_LOWV} < V_{VBUS} < V_{VBUS\_OVP}$  and  $V_{VBUS} > V_{BAT} + V_{SLEEP}$ ,  $L=1\mu H$ ,  $T_J = 25^\circ C$  unless otherwise noted)

SYMBOL	PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
<b>SWITCHING CONVERTER</b>						
$F_{SW}$	Switching Frequency		1000	1210	1420	kHz
$I_{HSFET\_OCP}$	HSFET Over Current Protection			3.6		A
$D_{MAX}$	Maximum duty cycle			100		%
<b>COLD/HOT THERMISTOR COMPARATOR</b>						
$V_{T1}\%$	$T_{COLD}$ (0°C) threshold, charge suspend if $V_{TS}$ is above the threshold	$V_{TS}$ rising, as percentage of $V_{PMID}$	73	73.5	74	%
$V_{T1}\%$		$V_{TS}$ falling, as percentage of $V_{PMID}$		71.5		%
$V_{T3}\%$	$T_{HOT}$ (45°C) threshold, charge suspend if $V_{TS}$ is below the threshold	$V_{TS}$ falling, as percentage of $V_{PMID}$	47	47.25	47.5	%
$V_{T3}\%$		$V_{TS}$ rising, as percentage of $V_{PMID}$		48.25		%
<b>THERMAL REGULATION AND THERMAL SHUTDOWN</b>						
$T_{REG}$	Thermal regulation			130		°C
$T_{SHUT\_RISE}$	Thermal shut down	Temperature rise		150		°C
$T_{SHUT\_FALL}$	Thermal shut down	Temperature fall		120		°C

## Typical Characteristics

( $L=1\mu\text{H}$ ,  $\text{CPMID}=10\mu\text{F}$ ,  $\text{CIN}=2.2\mu\text{F}$  and  $T_J = 25^\circ\text{C}$  unless otherwise noted)

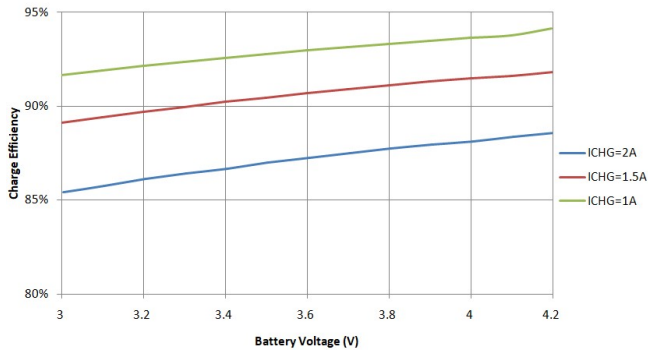


Figure 1. Battery Charge Efficiency ( $V_{\text{IN}}=5\text{V}$ )

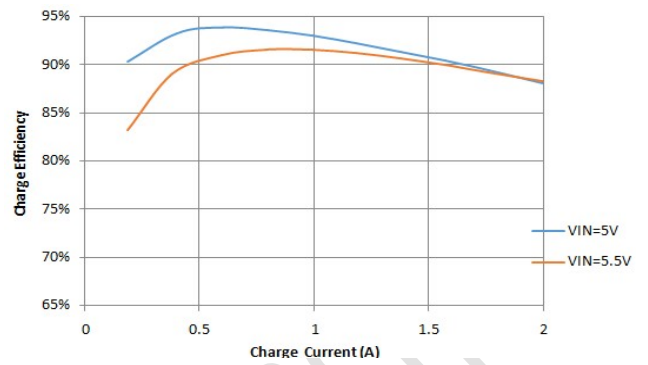


Figure 2. Battery Charge Efficiency ( $V_{\text{BAT}}=4\text{V}$ )

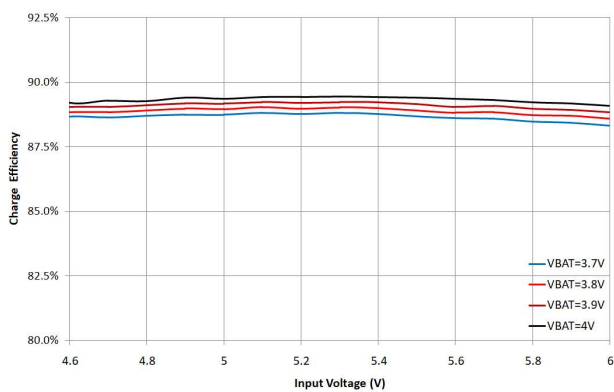


Figure 3. Charge Efficiency vs. Input Voltage ( $\text{ICHG}=2\text{A}$ )

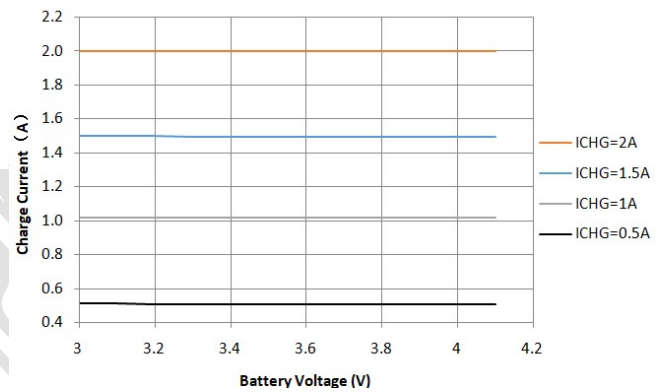
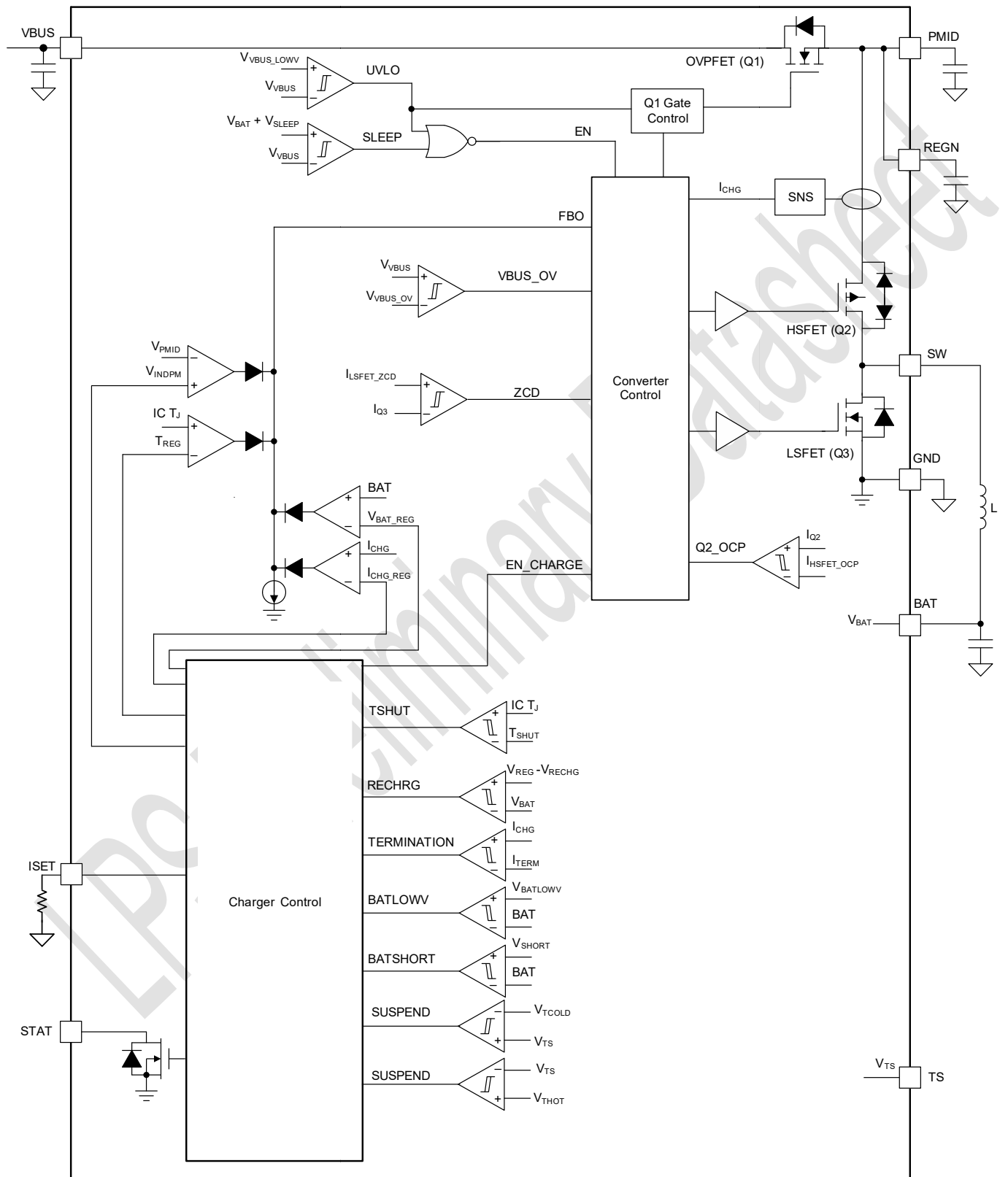


Figure 4. Charge Current vs. Battery Voltage

Functional Block Diagram



## Detailed Description

### Input Over Voltage Protection (OVP)

The LP4023 comprises of input over voltage protection followed by a Buck charger. During power-up from V<sub>BUS</sub>, OVPFET soft-start after V<sub>BUS</sub> reaches UVLO threshold V<sub>UVLO\_RISE</sub> for a delay time. Following the OVPFET soft-start, charger is enabled if charge mode condition is met. If the input voltage V<sub>BUS</sub> exceeds the OVP threshold, the P-channel OVPFET gate voltage is pulled to a reference voltage such that PMID voltage is clamped at V<sub>PMID\_CLAMP</sub>. Buck charger is connected between PMID and a battery.

### Charger Power-up

If ISET pin is not shorted, internal LDO successful power-up, if there is no faults detected, the device powers up and charge is enabled. The faults include:

- Input OVP fault:  $V_{VBUS} > V_{VBUS\_OVP}$
- TS cold/hot fault
- Junction temperature is above T<sub>SHUT</sub>

### Device Functional Mode

The device operates in different modes depending on V<sub>BUS</sub> voltage, battery voltage and ISET pin connection. The functional modes are listed in the following table.

Table 1: Device Functional Mode

MODE	CONDITIONS	CHARGE	STAT
ISET Pin Short (used as Enable/Disable)	ISET pin is shorted to GND	NO	OPEN
HiZ Mode	$V_{VBUS} < V_{UVLO}$	NO	OPEN
Sleep Mode	$V_{VBUS} > V_{UVLO}$ $V_{VBUS} < V_{BAT} + V_{SLEEP\_Z}$	NO	OPEN
Charge Mode	$V_{VBUS} > V_{UVLO}$ $V_{VBUS} > V_{BAT} + V_{SLEEP\_Z}$ $V_{VBUS} < V_{VBUS\_OVP\_RISE}$	YES	PULLED LOW
Charge Termination Mode	$V_{VBUS} > V_{UVLO}$ $V_{VBUS} > V_{BAT} + V_{SLEEP\_Z}$ $V_{VBUS} < V_{VBUS\_OVP}$ No faults and charge is terminated	NO	OPEN
Fault Mode	<ul style="list-style-type: none"> <li>• Input OVP</li> <li>• TS Cold/Hot</li> <li>• Thermal Shutdown</li> </ul>	NO	OPEN

## Battery Charge Profile

In Charge Mode as shown in the table of Device Functional Mode, the devices charge the battery in four sub-charge-modes: trickle charge, pre-charge, Constant Current (CC) charge and Constant Voltage (CV) charge as shown in Figure 5. If the battery voltage falls below  $V_{BAT\_SHORT\_FALL}$ , the battery charge battery with trickle charge current  $I_{BAT\_SHORT}$ , when the battery voltage rises above  $V_{BAT\_SHORT\_RISE}$  and below  $V_{BAT\_LOWV\_RISE}$ , the charger charges battery in precharge mode with charge current at  $I_{PRECHG}$ . Fast charge starts once battery voltage rises above  $V_{BAT\_LOWV\_RISE}$ . When battery voltage is close to battery charge voltage  $V_{BATREG}$ , the charger goes into CV mode and charge current starts to decreases. When charge current decreases below termination current  $I_{TERM}$ , charge is terminated and charge cycle ends. Following charge termination, if the battery voltage follows below  $(V_{BATREG} - V_{RECHG\_HYS})$ , a new charge cycle restarts.

### Trickle Charge

Under battery short condition, the device charges the battery at a fixed charge current  $I_{BAT\_SHORT}$  if the battery is below  $V_{BAT} < V_{BAT\_SHORT}$ . The trickle charge current is from the controlled P-channel HSFET.

### Precharge

The device charges the battery at 10% of programmed fast charge current  $I_{CHG}$  in precharge mode. Precharge is enabled in charge mode when the precharge condition  $V_{BAT\_SHORT\_RISE} < V_{BAT} < V_{BAT\_LOWV\_RISE}$  is met.

### Constant Current (CC) Charge

CC charge is also called fast charge. The device charges the battery from Buck converter at current level of  $K_{I_{CHG}} / R_{ISET}$ , where  $K_{I_{CHG}}$  is the gain of charge current setting.

### Constant Voltage (CV) Charge

With the battery voltage charged up, the BAT pin voltage reaches the battery regulation voltage  $V_{BATREG}$  and the charge current starts to decrease from fast charge current  $I_{CHG}$ . The actual battery voltage keeps increasing until charge termination is triggered.

### Charge Termination

The device terminates a charge cycle when the battery voltage is above recharge threshold  $(V_{BATREG} - V_{RECHG\_HYS})$  and the charge current is below termination current  $I_{TERM}$  for deglitch time  $t_{TERM}$ . The termination current threshold  $I_{TERM}$  is 10% of fast charge current  $I_{CHG}$ , which is set by the RISE resistor connected at ISET pin.

### Battery Recharge

Once a charge cycle is terminated, if battery voltage  $V_{BAT}$  decreases below the recharge threshold  $(V_{BATREG} - V_{RECHG\_HYS})$  and the charge mode conditions are met, the charger is enabled again. In addition to recharge, charge cycle starts if  $V_{VBUS}$  voltage is recycled or fault conditions are cleared or ISET pin is released from a short condition even with the battery voltage above the recharge threshold.

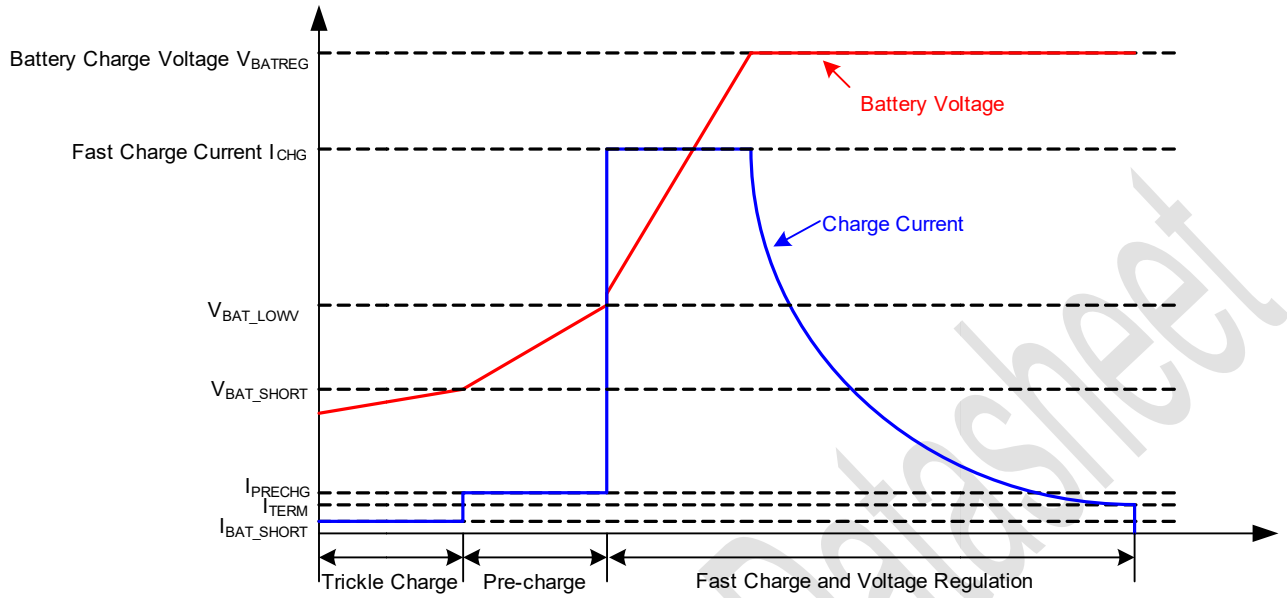


Figure 5. Battery Charge Profile

Table 2. Charge Current in Charge Mode

CHARGE MODE	BATTERY VOLAGE $V_{BAT}$	CHARGE CURRENT	TYPICAL VALUES
Trickle Charge	$V_{BAT} < V_{BAT\_SHORT\_FALL}$	$I_{BAT\_SHORT}$	60mA
Precharge	$V_{BAT\_SHORT\_RISE} < V_{BAT} < V_{BAT\_LOWV}$	$I_{PRECHG}$	10% of $I_{CHG}$
Fast Charge	$V_{BAT\_LOWV} < V_{BAT} < V_{BATREG}$	$I_{CHG}$	$K_{I_{CHG}} / R_{ISET}$
CV Charge	$V_{BAT\_LOWV} < V_{BAT} < V_{BATREG}$	$< I_{CHG}$	Variable

## Battery Temperature Monitoring

The charger device provides a single NTC thermistor input TS pin for battery temperature monitor. RT1 and RT2 resistor programs the cold temperature T1 and hot temperature T3. In the Equations (1) and (2), RNTC,T1 is NTC thermistor resistance value at temperature T1 and RNTC,T3 is NTC thermistor resistance values at temperature T3. VT1% and VT3% can be found in the Electronic Characteristics table. Select 0°C to 45°C for battery charge temperature range, then NTC thermistor 103AT-2 resistance are RNTC,T1 = 27.28 kΩ ( at 0°C) and RNTC,T3 = 4.91 kΩ (at 45°C). From Equation (1) and Equation (2), RT1 and RT2 are derived as below, which is the resistance to set the charge temperature range 0 to 45°C.

- RT1 = 4.52 kΩ
- RT2 = 23.2 kΩ

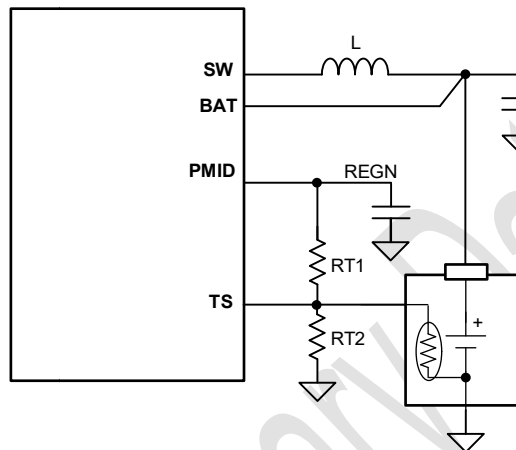


Figure 6. Battery Temperature Monitoring

$$RT2 = \frac{R_{NTC,T1} \times R_{NTC,T3} \times \left( \frac{1}{V_{T3}\%} - \frac{1}{V_{T1}\%} \right)}{R_{NTC,T1} \times \left( \frac{1}{V_{T1}\%} - 1 \right) - R_{NTC,T3} \times \left( \frac{1}{V_{T3}\%} - 1 \right)} \quad (1)$$

$$RT1 = \frac{\frac{1}{V_{T1}\%} - 1}{\frac{1}{RT2} + \frac{1}{R_{NTC,T1}}} \quad (2)$$

If TS is open, TS function is disabled. If TS function is not used, just leave TS pin open.

## Fault Mode

Any fault below triggers the charger into fault mode:

- Input OVP
- TS Cold/Hot
- Thermal Shutdown

In fault mode, the device stops charging. Once a fault is cleared, the charger goes back to charge mode if charge conditions are met.

## ISET Pin Short

If ISET pin is open, the charge current is minimized. If the ISET pin is shorted to GND ( $V_{ISET} < 0.35V$ ), the charge is disabled and STAT pin is open. ISET pin can be used as enable input for charge enable or disable. An open-drain GPIO in parallel with  $R_{ISET}$  can be connected to ISET pin to enable and disable charge. When ISET pin is released from short, the charger goes through soft-start process.

## Input Voltage Dynamic Power Management (VINDPM)

When the input current of the device exceeds the current capability of the power supply, the charger device regulates VBUS voltage by reducing charge current to avoid crashing the input power supply. To charge a battery, the input voltage must be higher than actual  $V_{INDPM}$  threshold. In VINDPM regulation, termination is temporarily disabled. VINDPM is enabled in both precharge and fast charge phase. There is no VINDPM regulation in trickle charge.

## Maximum Duty Cycle Dmax and 100% Duty Cycle

The Buck converter implemented HSFET maximum duty cycle and 100% duty cycle. When a weak input source (due to long input cable or lower power level of an adaptor) is connected at VBUS, the HSFET duty cycle increases. If Dmax is reached and the closed-loop regulation still cannot regulate current or voltage, then HSFET turns on with 100% duty cycle. By implementing 100% duty cycle, the Buck converter operates in pass-through mode and charge current is maximized and efficiency jumps to higher level.

## Thermal Regulation (TREG)

The device monitors the junction temperature  $T_J$  to avoid overheating the chip and limit the device surface temperature. When the internal junction temperature exceeds thermal regulation limit  $T_{REG}$ , the device lowers down the charge current. During thermal regulation, the average charging current is usually below the programmed battery charging current. In thermal regulation, termination is temporarily disabled.

## Thermal Shutdown (TSHUT)

The devices have thermal shutdown built in to turn off the charger when device junction temperature exceeds  $T_{SHUT}$ . The charger is re-enabled when the junction temperature is  $25^{\circ}C$  below  $T_{SHUT}$ . During thermal shutdown, charge is suspended and the charger goes into fault mode.

## Application and Implementation

### Application Information

As shown in Figure 7, the device can be used for general purpose high efficiency fast charger. The charge current is programmable by a resistor from ISET pin to GND. The charge can be enabled or disabled by a MCU GPIO to pull ISET pin high.

### Application Schematic

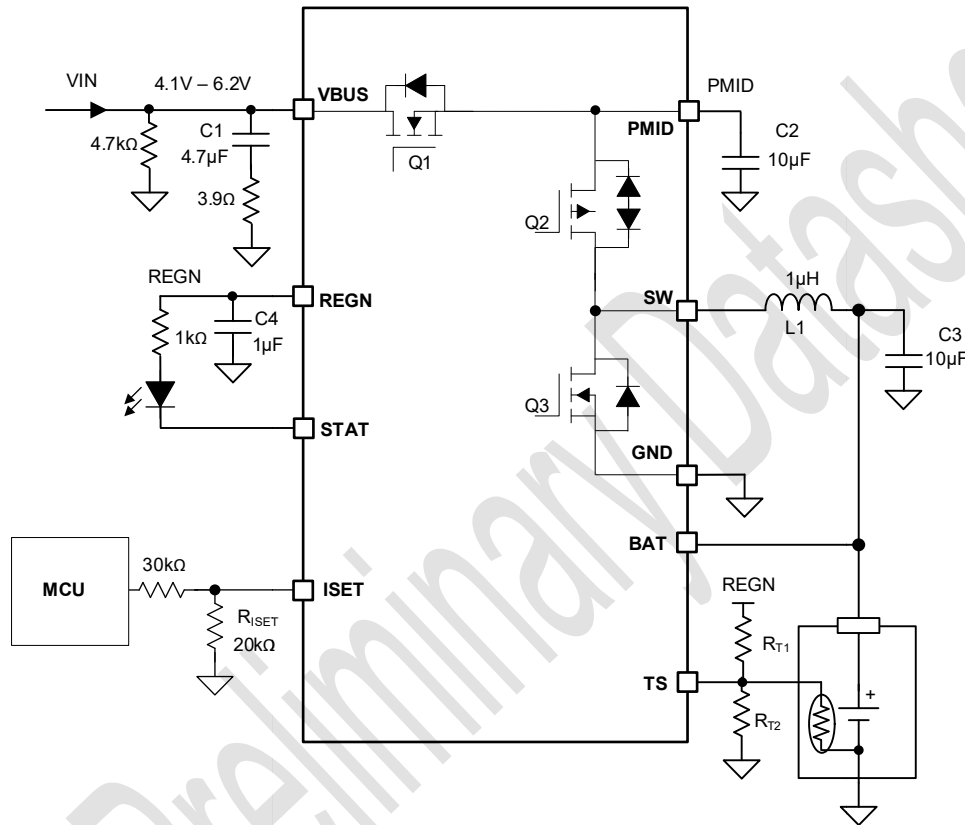


Figure 7: Typical Applications Schematic (ICHG=2A)

### Charge Current Setting

The charger current is set by the resistor value at the ISET pin according to the equation below:

$$I_{CHG} \text{ (A)} = K_{ICHG} \text{ (A} \cdot \text{k}\Omega) / R_{ISET} \text{ (k}\Omega) \quad (3)$$

$K_{ICHG}$  is current setting gain that is listed in Electrical Characteristics table and  $R_{ISET}$  is the resistor value from ISET pin to GND.  $K_{ICHG}$  is typically 40 (A·kΩ).

### Input Hot Plug-In

To attenuate potential input voltage spike caused by cable parasitic inductance during input hot plug-in, there is a 3.9Ω resistor in series with the 4.7μF input capacitor. The 4.7kΩ resistor at input is used to discharge the input capacitor in case there is contact bounce.

## Application and Implementation (Continued)

### Application Curves

(Schematic as shown in Figure 7)

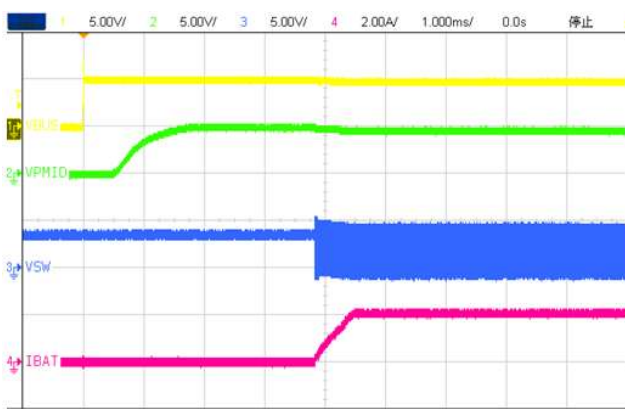


Figure 8. Power-up from VBUS  
( $V_{VBUS}=5V$ ,  $V_{BAT}=3.8V$ ,  $I_{CHG}=2A$ )

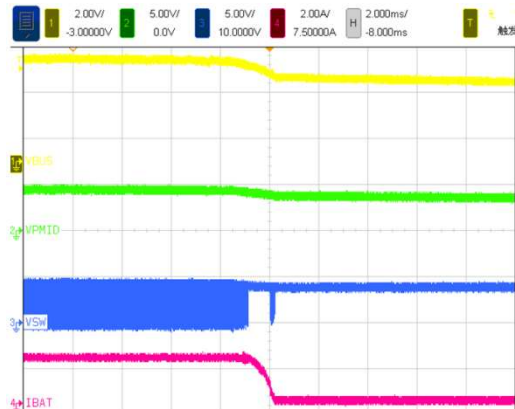


Figure 9. Power down from VBUS  
( $V_{VBUS}=5V$ ,  $V_{BAT}=3.8V$ ,  $I_{CHG}=2A$ )

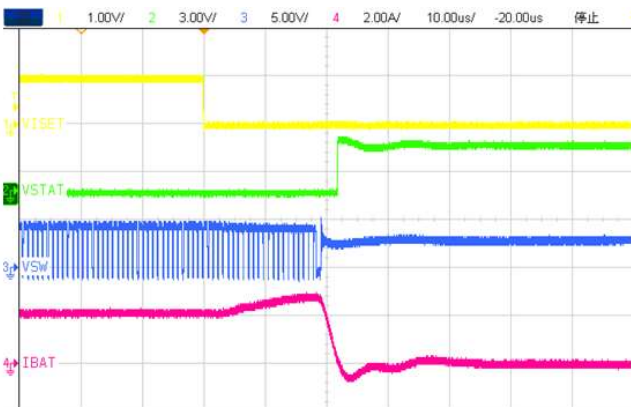


Figure 10. ISET Short  
( $V_{VBUS}=5V$ ,  $V_{BAT}=3.8V$ ,  $I_{CHG}=2A$ )

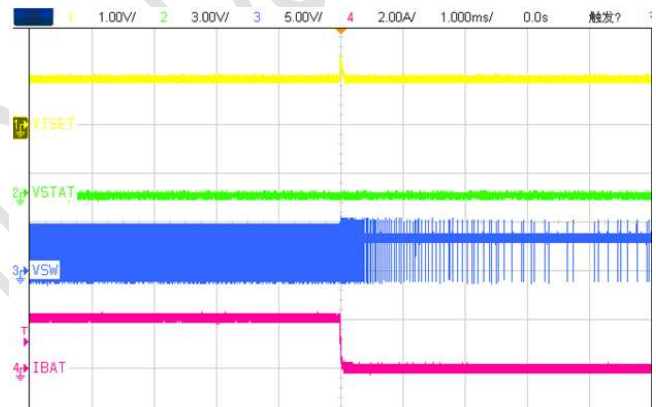


Figure 11. RISET Floating  
( $V_{VBUS}=5V$ ,  $V_{BAT}=3.8V$ ,  $I_{CHG}=2A$ )

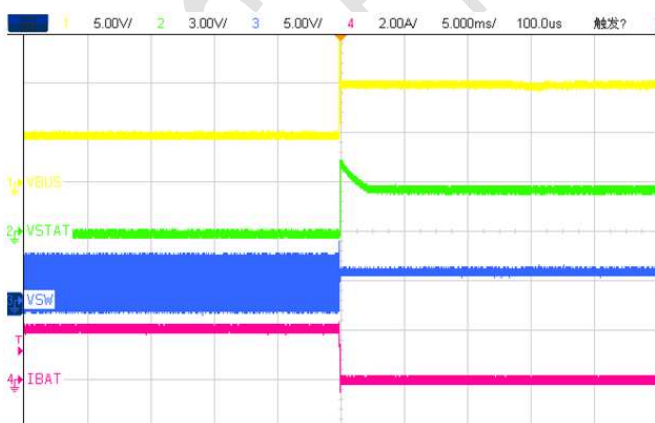


Figure 12. Input Over Voltage  
( $V_{VBUS}=5V$  to  $15V$ ,  $V_{BAT}=3.8V$ ,  $I_{CHG}=2A$ )



## PCB Layout Guideline

Appropriate PCB layout is important in the power supply design. Good PCB layout minimizes EMI and noises, allows good output voltage regulation and achieves higher efficiency. The following design considerations are recommended:

- Decouple PMID and VBUS pins to GND on top layer and place decoupling capacitors as close to those pins as possible. Always avoid vias if possible because they have parasitic inductance and resistance. If vias are inevitable, always use multiple vias in parallel to decrease parasitics on power traces.
- Connect GND pad to the ground plane(s) on the IC bottom side with multiple vias that is for both heat dissipation and electrical connection.
- Minimize switching SW node size and trace lengths and keep it away from ISET and BAT traces.
- A 2-layer PCB layout example is shown in Figure 13.

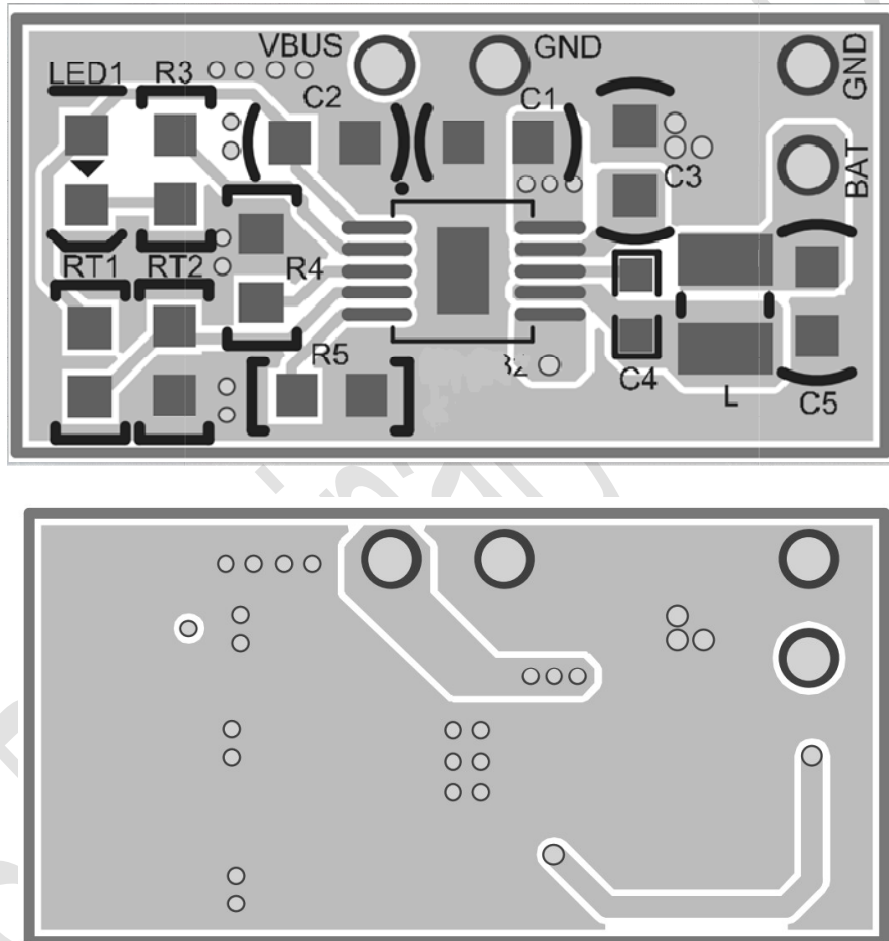
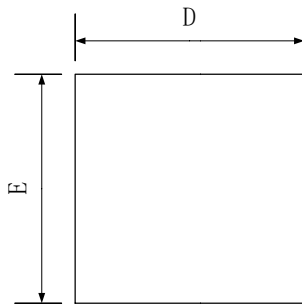


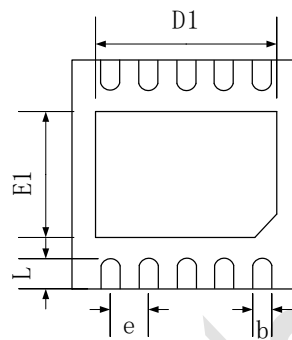
Figure 13. 2-layer PCB Layout Example

Packaging Information

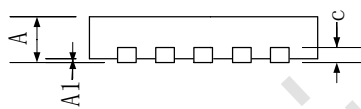
DFN-10



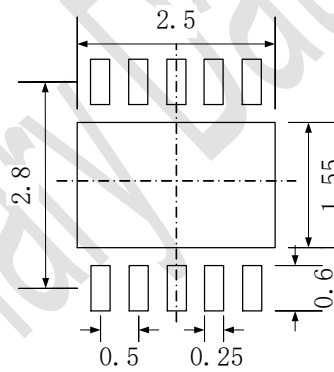
TOP VIEW



BOTTOM VIEW



SIDE VIEW

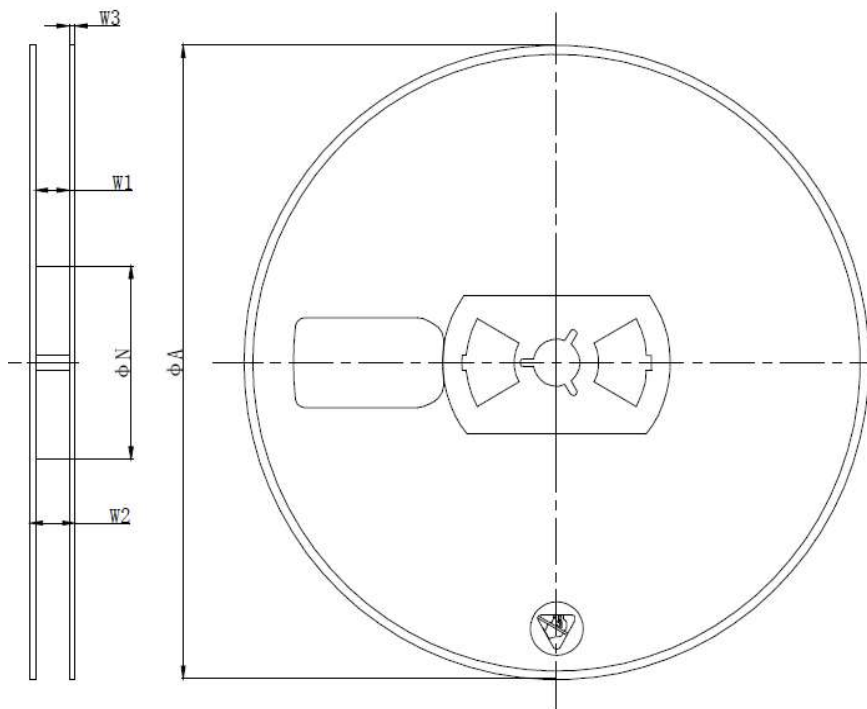


Recommended Land Pattern

SYMBOL	MILLIMETER		
	MIN	NOM	MAX
A	0.70	0.75	0.80
A1	0.00	0.02	0.05
B	0.18	0.25	0.30
C	0.20 REF		
D	2.90	3.00	3.10
D1	2.40	2.50	2.60
E	2.90	3.00	3.10
E1	1.45	1.55	1.65
E	0.50 BSC		
L	0.30	0.40	0.50

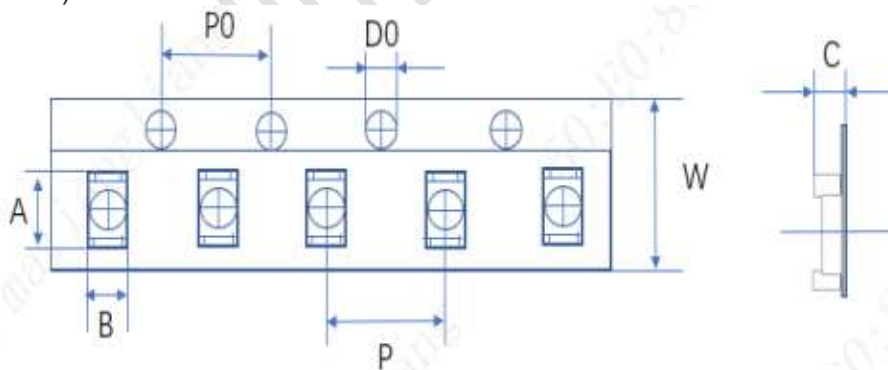
## Carrier Information

Reel Dimensions (Unit: mm)



Device	$\Phi A$	W2
LP4023QVF	329±3	16.4±3

Tape Dimension (Unit: mm)



Device	A	B	P0	P	D0	W	C
LP4023QVF	3.4±0.30	3.4±0.30	4.00±0.10	8.00±0.20	1.55±0.10	12.00±0.30	1.1±0.20

Pin 1 and Tape Feeding Direction